## [NAME OF DOCUMENT] Claims

[Claim 1]

A contact pin for contacting a terminal of an electronic device to supply said electronic device with a signal, provided with

a first conductive layer composed of a first conductive material with a high hardness and

a second conductive layer composed of a second conductive material with a lower hardness than said first conductive material.

[Claim 2]

A contact pin as set forth in claim 1, wherein said first conductive material has a hardness higher than the oxide film formed on the terminal of said electronic device.

[Claim 3]

A contact pin as set forth in claim 1, wherein said second conductive material has a lower hardness than the oxide film formed on the terminal of said electronic device.

[Claim 4]

A contact pin as set forth in claim 1, wherein both said first conductive layer and said second conductive layer are exposed at the front end face of the contact pin at the wafer side.

[Claim 5]

A contact pin as set forth in claim 1, wherein said first conductive layer is formed at the outside from said second conductive layer.

[Claim 6]

A contact pin as set forth in claim 1, wherein said first

conductive layer is formed so as to be in close contact with the outside of said second conductive layer.

[Claim 7]

A contact pin as set forth in claim 1, wherein said contact pin is formed finely tapered at its front end.

[Claim 8]

A contact pin as set forth in claim 1, wherein the pin is further provided with a base material at the outside of which the first conductive layer and second conductive layer are formed,

said base material being arranged inside said contact pin with the front end of that base material separated by a predetermined distance from the front end of said contact pin.

[Claim 9]

A contact pin as set forth in claim 1, wherein a plurality of at least of said first conductive layer or said second conductive layer is provided.

[Claim 10]

A probe card having contact pins of any of claims 1 to 9 electrically connected to a test head of an electronic device test apparatus and a board upon one main surface of which said contact pins are provided, said contact pins being brought into contact with terminals of an electronic device to test said electronic device.

[Claim 11]

An electronic device test apparatus having a test head to which a probe card of claim 10 is electrically connected.